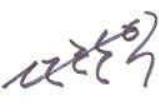




Approval Sheet

Products	Dielectric Chip Antenna		
Customer	Diostech		
Model			
Customer CODE			
Supplier	PARTRON		
Supplier CODE	ACS2450HBAHS2		
Diostech	By designed	By checked	By approved
PARTRON	By designed	By checked	By approved
			
	Research 2P	Quality Assurance	Laboratory
	Chanik.Jeon	Kwang-Gyu.Lee	Byoung-Jun.Yim
	01/02	01/02	01/02

2007 . 01. 02



33 Banwol-dong, Hwaseong-si, Gyeonggi-do, Korea 455-300
Tel : 82-31-201-7870~6
Fax : 82-31-201-7800
www.partron.co.kr

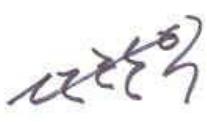


MSL Level 1

SPECIFICATION

MODEL : ACS2450HBAHS2

DIELECTRIC CHIP ANTENNA

By designed	By checked	By approved
		
Research, 2P	Quality Assurance	Laboratory
Chan-Ik.Jeon	Kwang-Gyu.Lee	Byoung-Jun.Yim
01/02	01/02	01/02

2007 . 01. 02



33 Banwol-dong, Hwaseong-si, Gyeonggi-do, Korea 455-300
Tel : 82-31-201-7870~6
Fax : 82-31-201-7800
www.partron.co.kr

- Contents -

1. Revision History	1 p
2. Electrical Characteristics	2 p
3. Mechanical Characteristics	7 p
4. Measurement Process	10 p
5. Primary Inspection List	11 p
6. Reliability Condition	12 p
7. Soldering Condition	13 p
8. Attention	13 p
9. Packing	14 p
10. Process Control	16 p
11. RoHS Data	19 p



1. Revision

2. Electrical Characteristics

2.1 Single Element Spec

ITEM	SPEC
Frequency Range [MHz]	2400 ~ 2485
SWR [Max]	3 : 1
Bandwidth [MHz]	85
Gain (Peak / Avg) [dBi]	0.0 / -2.0

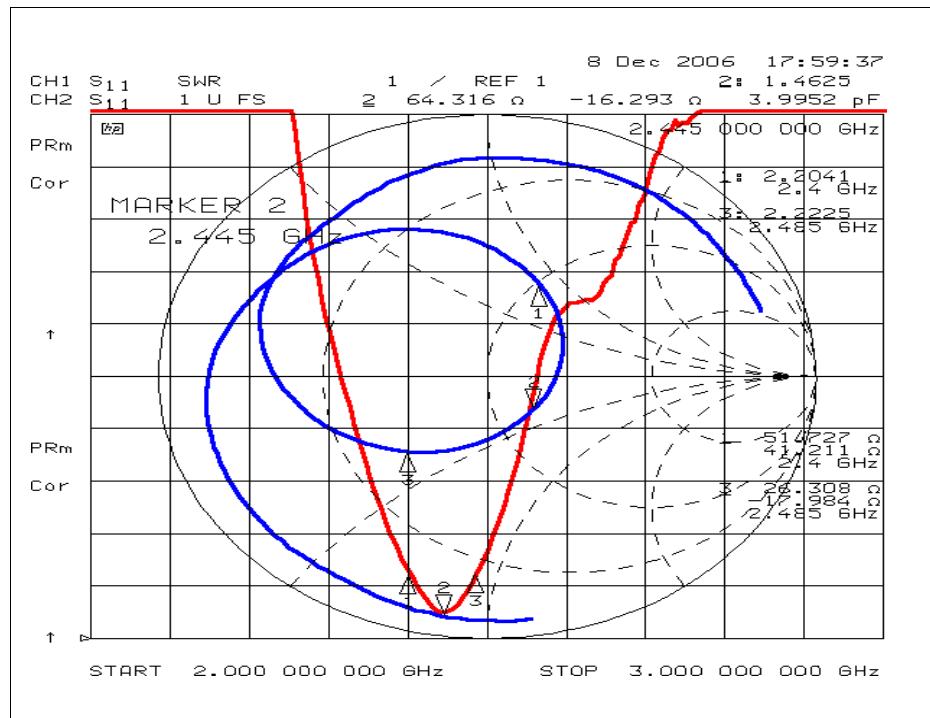
2.2 Set Condition

ITEM	SPEC
Frequency Range [MHz]	2400 ~ 2485
VSWR [Max]	3 : 1
Bandwidth [MHz]	85
Polarization	Linear
Gain[dBi]	Total Gain (Peak / Avg) [dBi]
	Peak
	Average
	Peak

2.3 Test Fixture Condition

ITEM	SPEC	CTQ
Frequency Range [MHz]		
SWR [Max]		
Bandwidth [MHz]		

2.3 S11 Graph of Set Condition

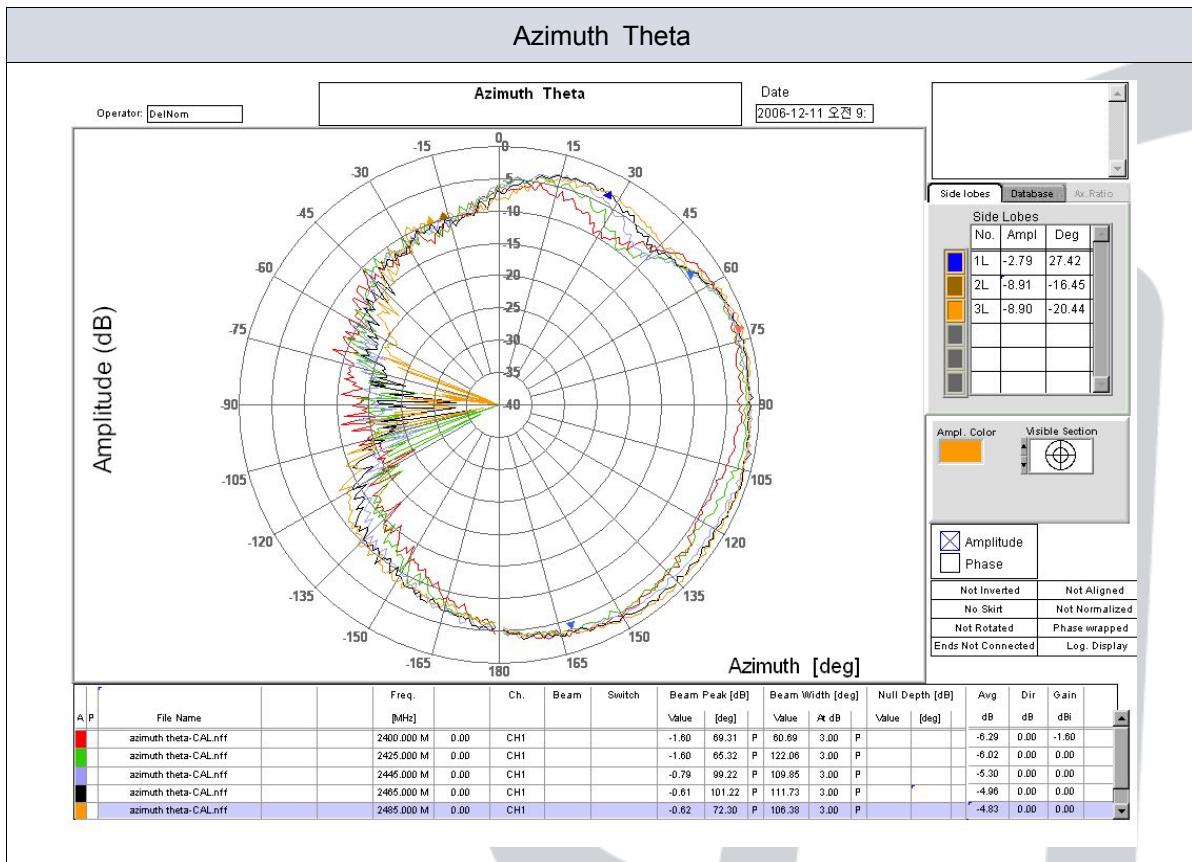


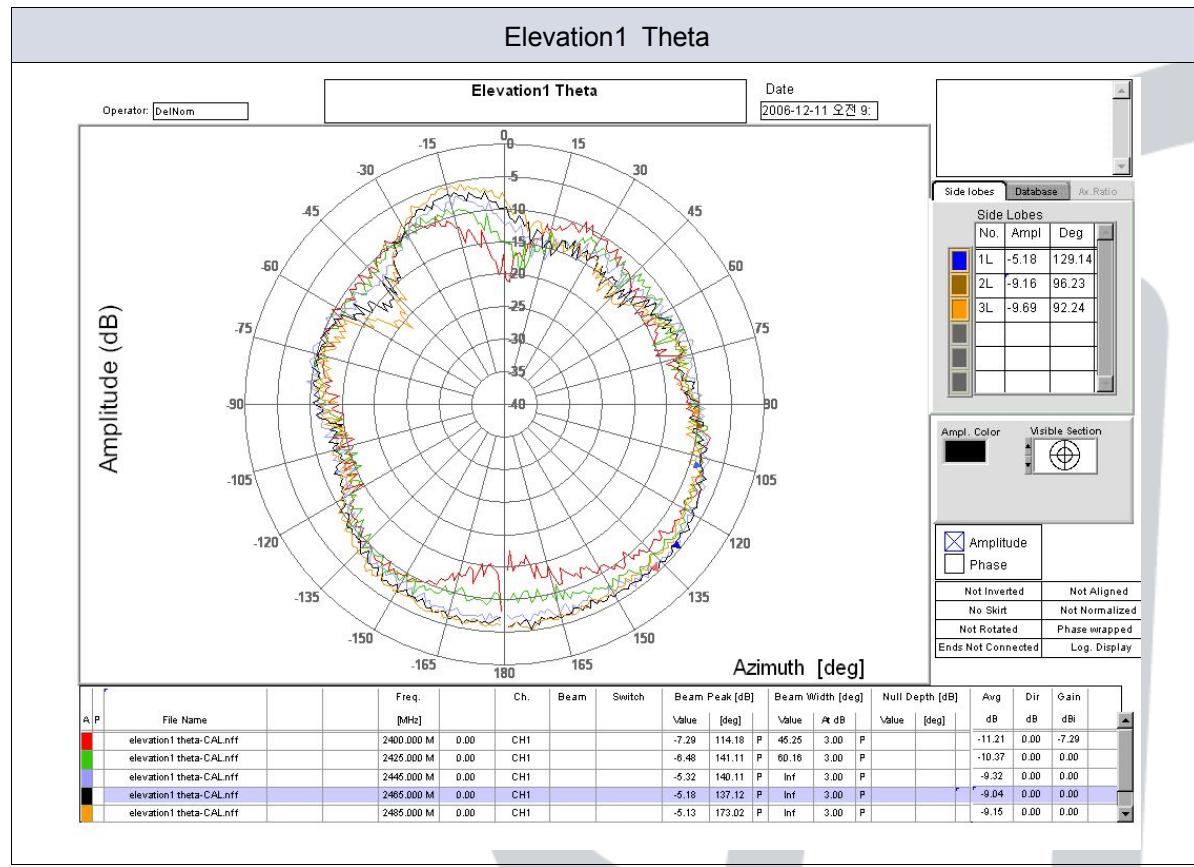
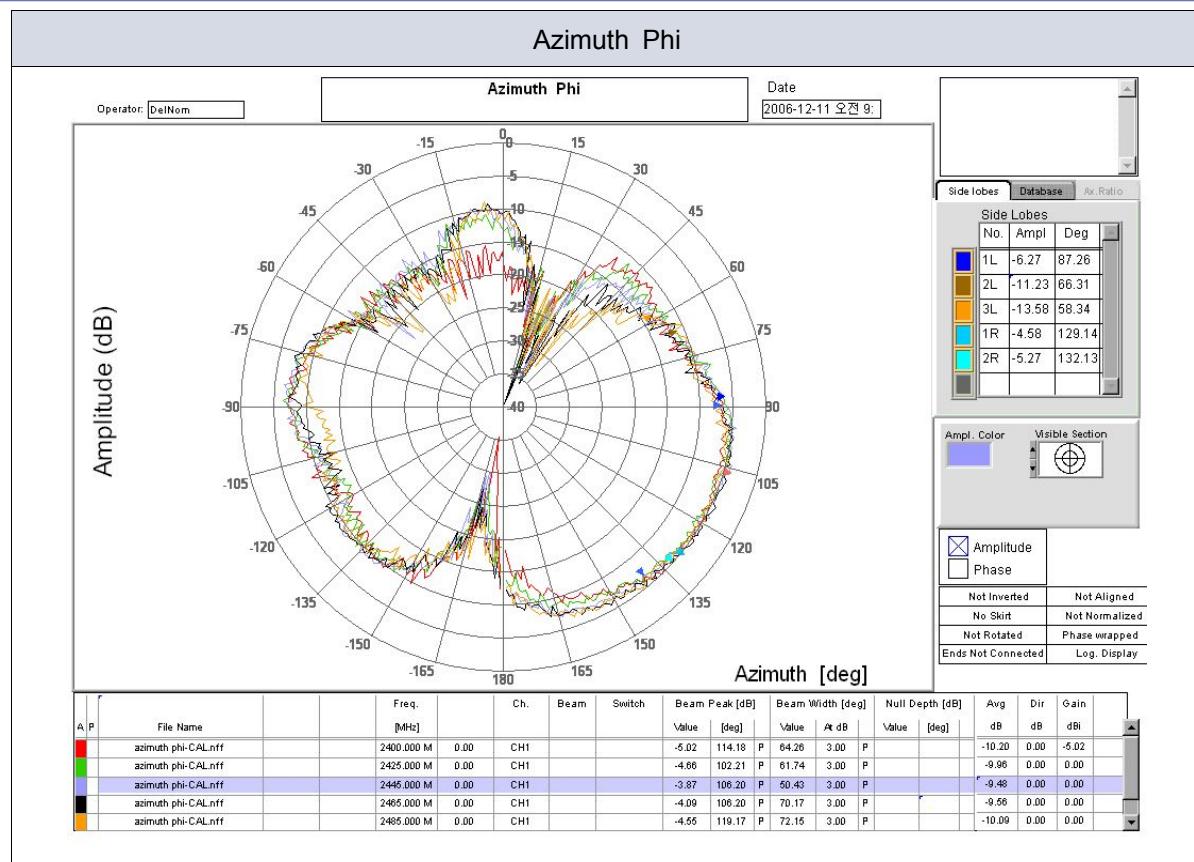
2.4 S11 Graph of Test Fixture Condition

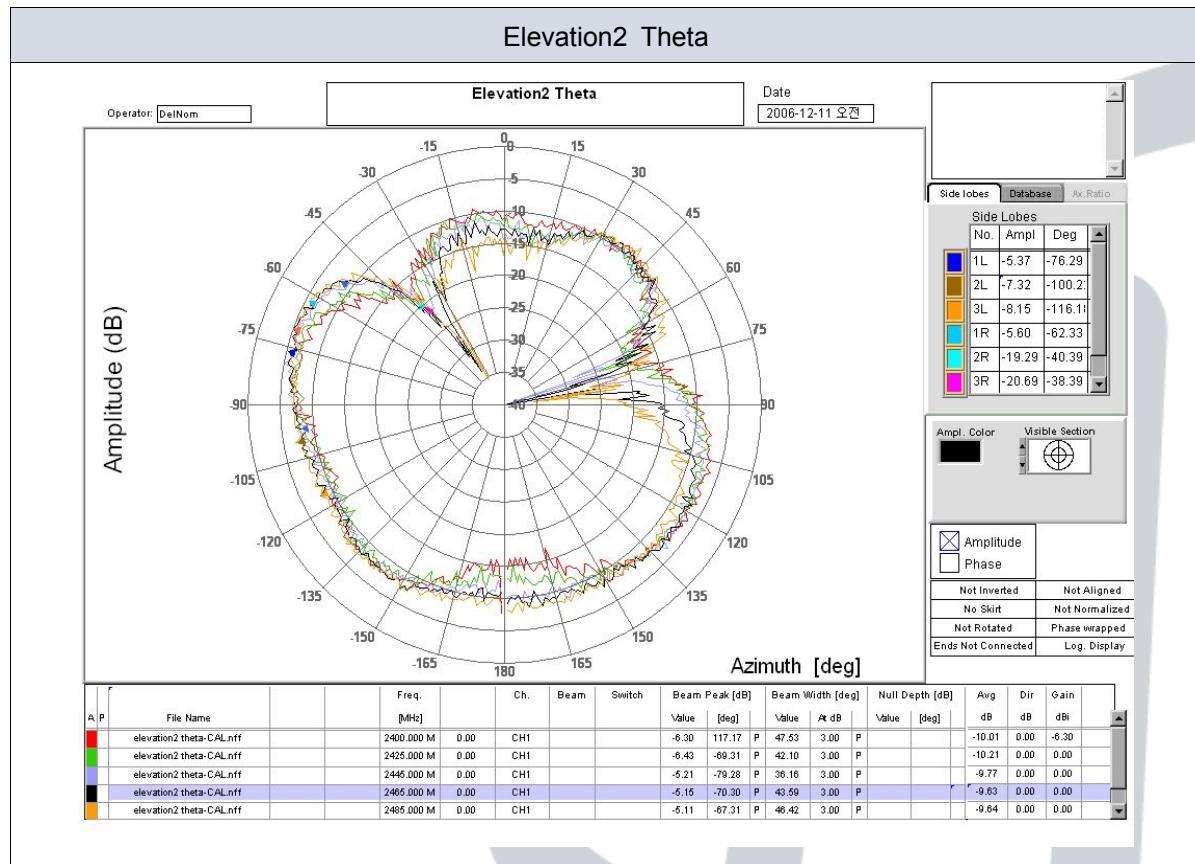
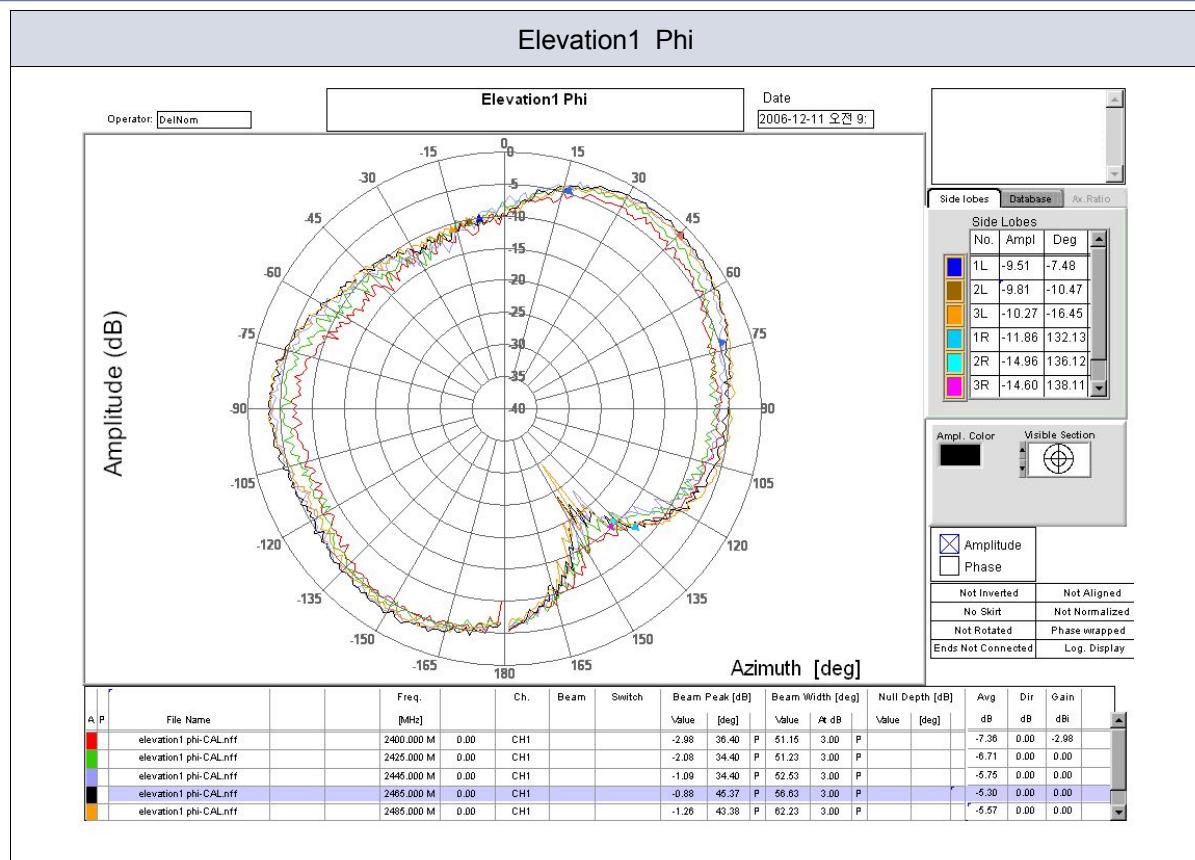
CTQ

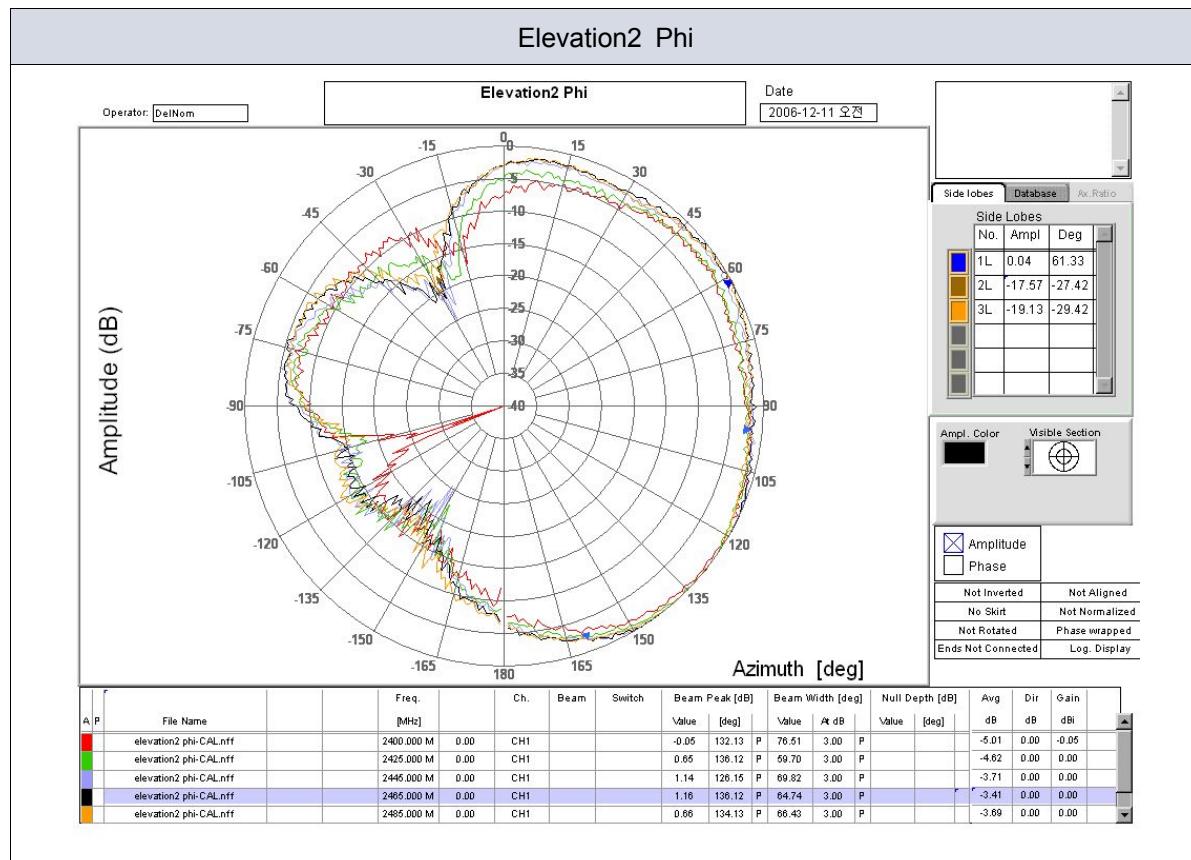
2.5 Radiation Pattern

Azimuth Plane	Elevation 1 Plane	Elevation2 Plane
Theta	Vertical field of measured plane	
Phi	Horizontal field of measured plane	









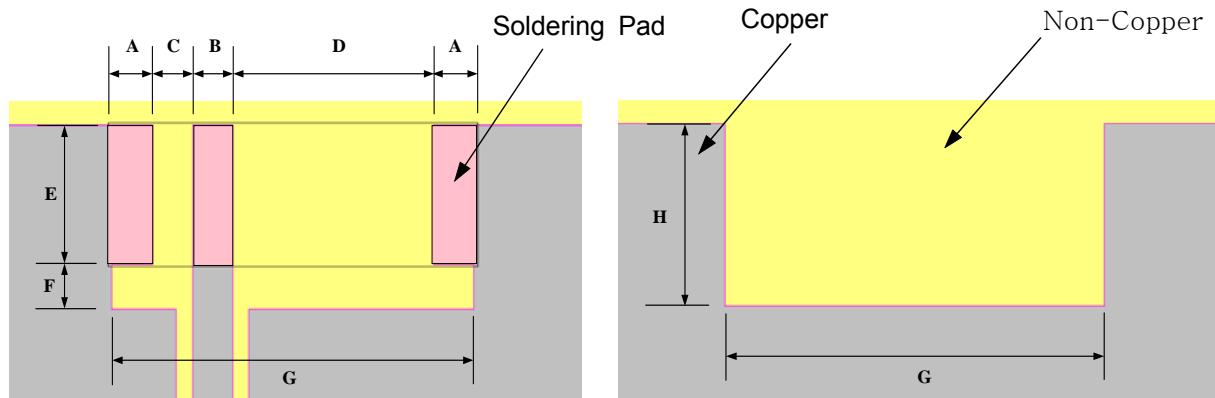
3. Mechanical Characteristics

- The structure is materialized printing Ag paste at the dielectric block

3.1 Structure and Material

Material	Dielectric Block (MMS-08)	3D Structure		
		Ag Paste (Metech)	Dielectric Block	Ag Paste
Size [mm]	W = 2.0±0.15			
	L = 8.0±0.15			
	T = 1.2±0.15			
Temperature [°C]		- 40 ~ +80		
Humidity [%]	At the normal temperature, RH 100			

3.2 PCB Layout & Soldering Pad Dimension



Top Layout

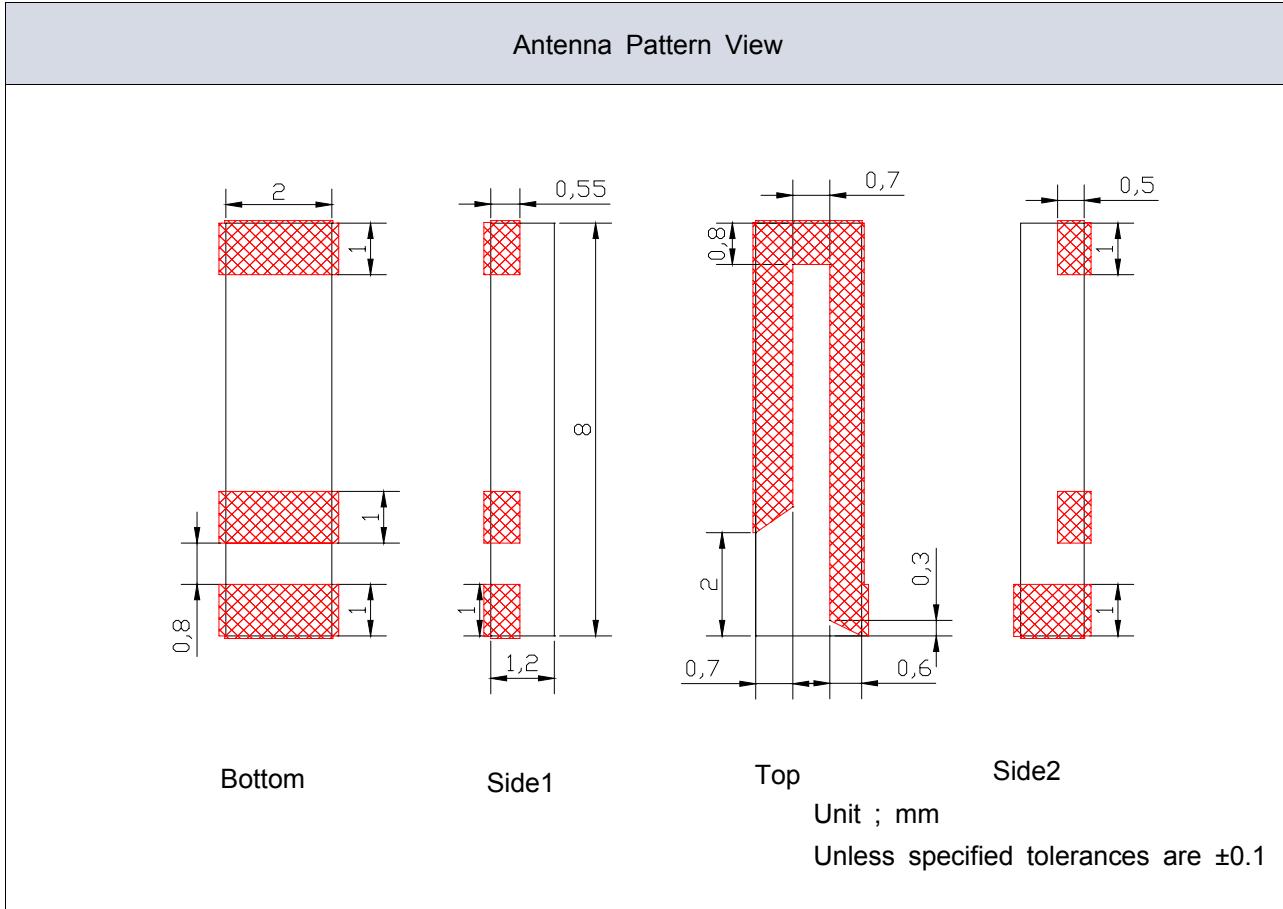
Bottom Pattern

Parameter	A	B	C	D	E	F	G	H
Value[mm]	1.1	1.0	0.8	4.2	2.2	1.0	8.0	3.0

Unit ; mm

Unless specified tolerances are ± 0.1

3.3 Antenna Pattern Dimension

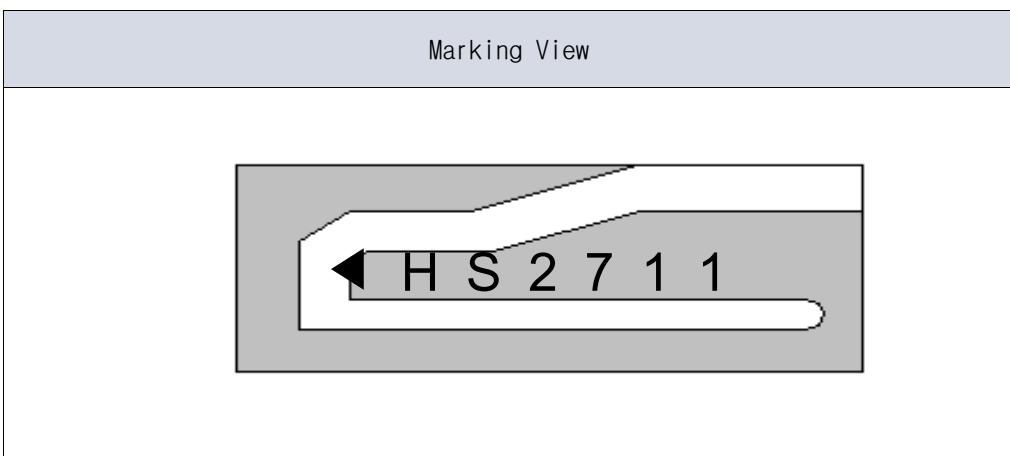


3.4 LOT Notation

7	1	1
①	②	③

- ① Year ; 1 - 2001, 2 - 2002, 5 - 2005
- ② Month ; 1 - January, 2 - February 9 - September, A - October, B - November ..
- ③ Date : 1 - 1st, 2 - 2nd A - 10th, B - 11th

3.5 Marking



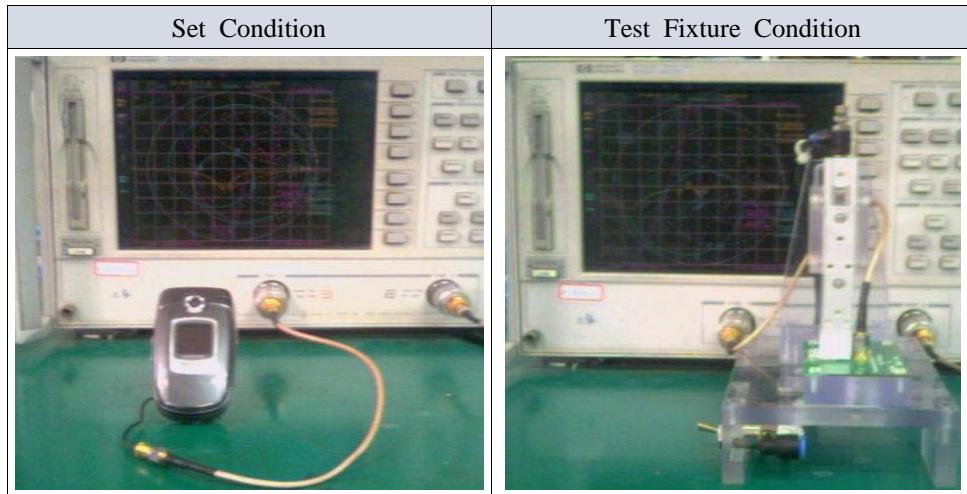
◀	H	S	2	7	1	1
①	②	③	④	⑤		

- ① Input Signal
- ② Serial
- ③ Year; 1 - 2001, 2 - 2002, 5 - 2005
- ④ Month ; 1 - January, 2 - February 9 - September, A - October, B - November
- ⑤ Date : 1 - 1st, 2 - 2nd A - 10th, B - 11th

4. Measurement Process

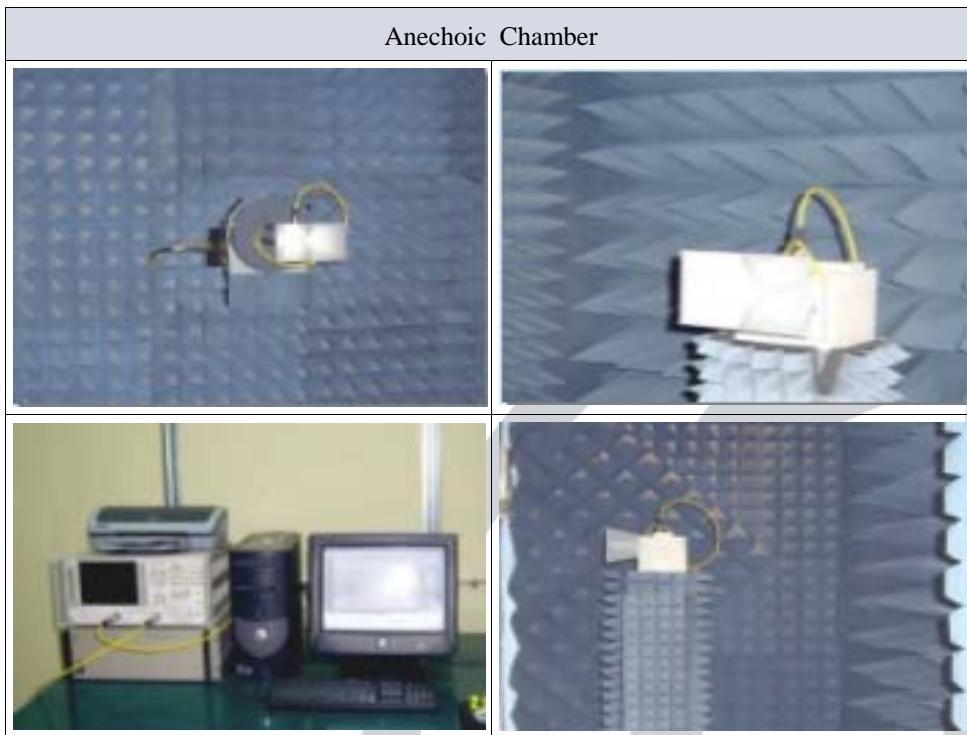
4.1 SWR/Returnloss

The SWR/Returnloss is measured by Network Analyzer



4.2 Gain

The Antenna Gain is measured using the set at Anechoic Chamber



5. Primary Inspection List

Item	Electrical Characteristic [MHz] 		Mechanical Dimension [mm] 		
	VSWR 3.0 Max		W=2.0±0.1	L=5.0±0.1	T=1.2±0.1
Standard	2270 MHz	2350 MHz			
1	1.51	2.28	2.03	8.01	1.25
2	1.56	2.10	2.02	8.02	1.24
3	1.56	2.15	2.03	8.02	1.24
4	1.56	2.03	2.04	8.01	1.26
5	1.55	1.93	2.04	8.02	1.25
6	1.68	1.88	2.05	8.03	1.25
7	1.66	1.91	2.04	8.00	1.23
8	1.58	2.09	2.03	8.01	1.24
9	1.70	1.94	2.05	8.03	1.26
10	1.56	2.03	2.04	8.02	1.24
11	1.60	2.13	2.06	8.01	1.25
12	1.62	1.90	2.04	8.01	1.25
13	1.64	1.95	2.03	8.00	1.23
14	1.60	2.03	2.04	7.99	1.24
15	1.60	2.13	2.03	8.03	1.24
16	1.63	2.06	2.05	8.02	1.25
17	1.61	2.02	2.04	8.01	1.24
18	1.58	1.97	2.04	8.02	1.25
19	1.62	1.98	2.05	8.00	1.24
20	1.61	2.01	2.03	8.01	1.26
X	1.61	2.02	2.04	8.01	1.24
σ	0.04	0.10	0.01	0.01	0.01
Cpk	9.03	2.35	2.45	2.61	2.58
	OK	OK	OK	OK	OK

6. Reliability Condition

6.1 ENVIRONMENT TEST

ITEM	TEST CONDITION	LIMIT
High Temperature Resistance	+85°C±3°C, 120hr±2hr	*After the test, specimen would be kept at 25°C±5°C for 1 hours
Low Temperature Resistance	-40°C±3°C, 120hr±2hr	*specimen sheet meet the electrical specification
Humidity Resistance	+60±3°C, RH90~95%, 120hr±2hr	

6.2 Thermal Shock Test, Reflow Test

ITEM	TEST CONDITION	LIMIT
Thermal Shock	-40°C±3°C(2Hr) ↔ +85°C±3°C(2Hr) cycle : 15cycle recovery time : within 5min	SAME as 6-1
Reflow	Pre Heating : 140±10°C, 60~120 sec peak Heating : 240°C, 10sec Max	

6.3 Mechanical Test

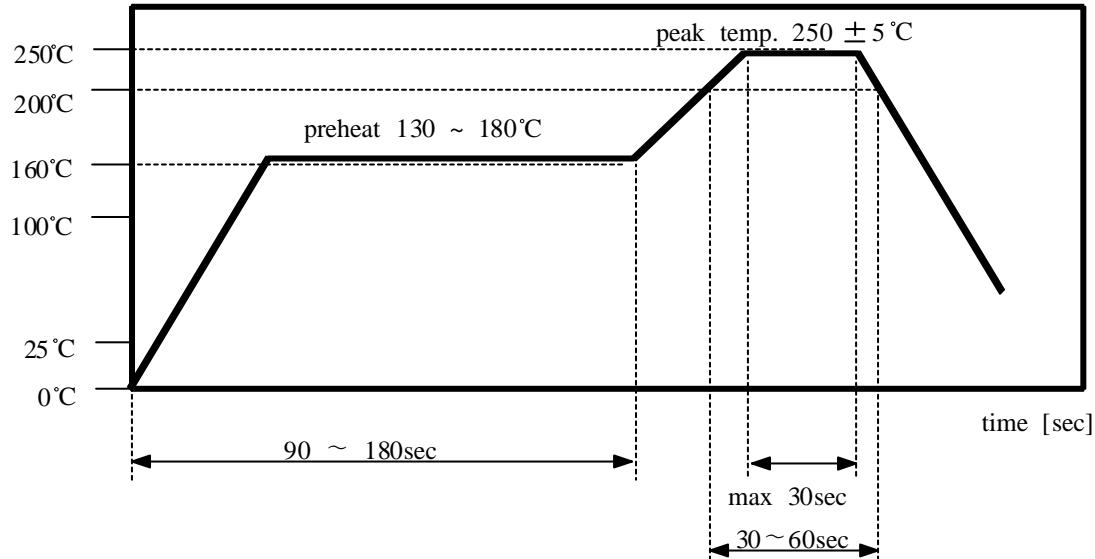
ITEM	TEST CONDITION	LIMIT
Random Vibration	Frequency 10~500Hz - 10 ×9.8m/s ² (G) Sweep time 15min, X.Y.Z each 5 times	*After the test, specimen sheet meet the electrical specification
Drop	Height 120cm, 12 times Height 152cm, 19 times	

6.4 Reliability Test Result

* Appendix

7. Soldering Condition

7.1 Reflow Soldering



7.2 Manual Soldering

Pre-heating Temperature : 120°C , 60 ~ 300 sec.

Soldering Temperature : 340°C±5°C , 5sec max per each terminal

8. Attention

8.1 Temperature Condition

	Range of Temperature	unit
Application	-40 ~ +85	°C
Keeping	-40 ~ +85	°C

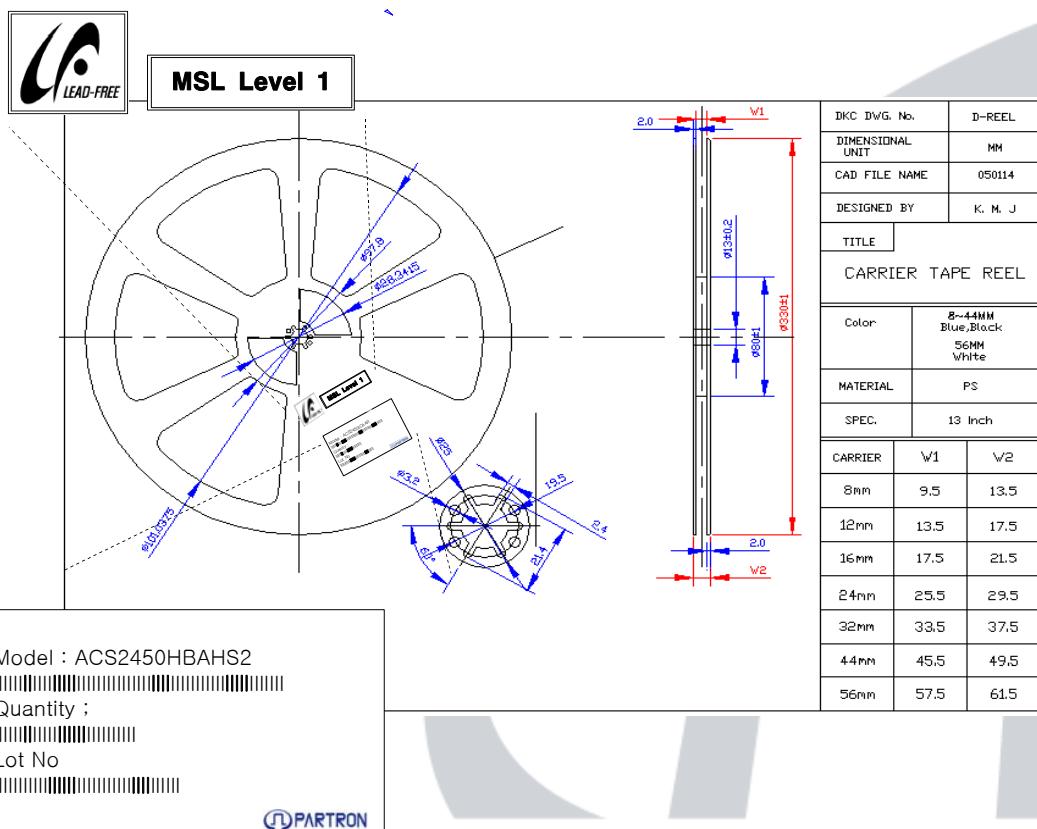
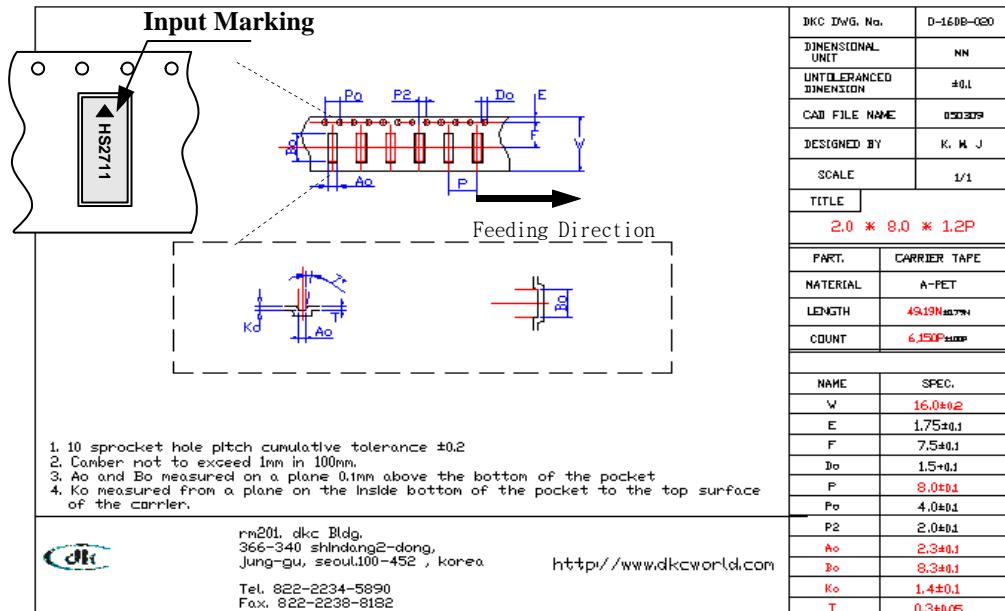
8.2 MSL LEVEL 1 (JEDEC J-STD-020C)

	Floor Life		Soak Requirements	
	Time	Conditions	Time	Conditions
1	Unlimited	= < 30°C / 85%RH	168+5/-0	= < 85°C / 85%RH

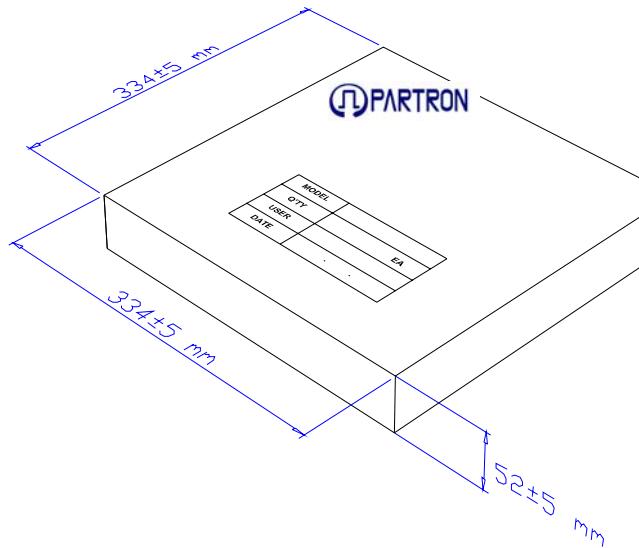
9. Packing

9.1 Carrier/Reel

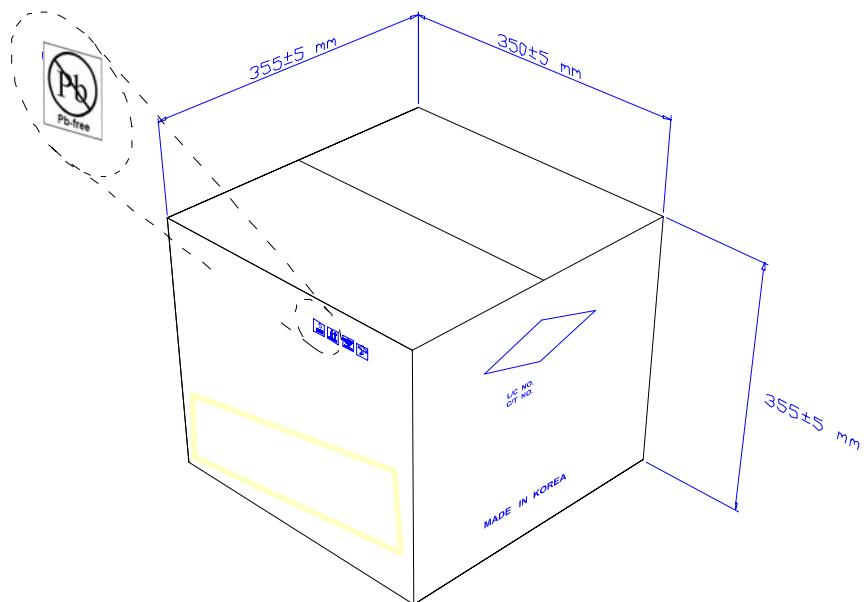
Material	Surface Resistance	Method
PET	Typical $10^8\Omega$	Heat Press



9.2 Box Specification



Material : SK/S/K-B
Cardboard box



10. Process Control

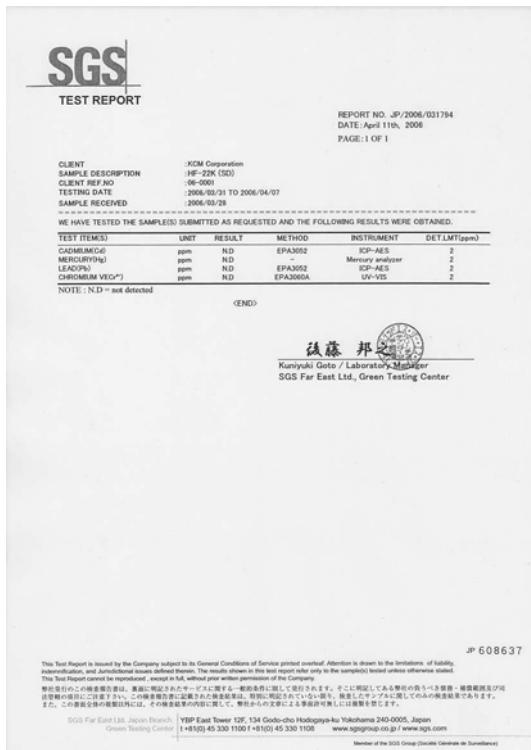
Product		Issued/Revision		Process Control					Record	By designed	By checked	By approved	
CHIP ANTENNA		Issued	04.04.06						PRCP-C001				
Input Materials	FLOW CHART		Process name	Management of Factors					Management of quality				
	preparation	Main Process		Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record
Ceramic POWDER		Import Inspection							shrinking rate permittivity	refer to Guide Sheet	Micrometer Network	10ea/LOT	C/sheet
POWDER lubricant		powder	Mixer						mixing	POWDER lubricant	Scale	PER MIXING	-
		Shaping	Press	pressure Mold Condition	refer to Guide Sheet	Per LOT 1/day	parameter C/SHEET	dimension	refer to Guide Sheet	Micrometer scale Calculated Visual	5/100EA 10ea/lot	LOT CARD	Exhaust
		Plasticity	Plasticity Hole	SETTER Outside Temperature PROFILE	refer to Guide Sheet	all 2/day 1/month	C/sheet	weight density aspect					
		Block						wide length shape	refer to Guide Sheet	Micrometer Calipers Visual Inspection	20ea/LOT 20ea/LOT all	C/sheet	Exhaust
AG PASTE		SIDE1 PAD Printing	Printer screen	Squeeze velocity/presure SNAP	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework
		Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework

Product			Issued/Revision		Process Control					Record	By designed	By checked	By approved	
CHIP ANTENNA			Issued	04.04.06						PRCP-C001				
Input Materials	FLOW CHART		Process name	Management of Factors					Management of quality					
	preparation	Main Process		Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
AG PASTE			SIDE 2 PAD Printing	Printer screen	Squeeze velocity/pressure SNAP	refer to Guide Sheet	1/day	-	PATTERN Dimension aspect	refer to Guide Sheet	Microscope	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
			Baking	Baking Hole mesh net	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework
AG PASTE			TOP printing	Printer screen	Squeeze velocity/pressure SNAP	refer to Guide Sheet	1/day	-	PATTERN dimension	refer to Guide Sheet	measure	10ea/3Jig	c/sheet	Rework
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
AG PASTE			BOTTOM PAD Printing	printer screen	Squeeze velocity/pressure SNAP	refer to Guide Sheet	1/day	-	PATTERN dimension aspect	refer to Guide Sheet	measure	10ea/3Jig	c/sheet	Rework
			CTQ								Microscope			

Product			Issued/Revision		Process Control				Record	By designed	By checked	By approved		
CHIP ANTENNA		Issued	04.04.06	Revised	05.04.03	PRCP-C001								
Input Materials	FLOW CHART		Process name	Management of Factors				Management of quality						
	preparation	Main Process		Equipment Name	Checked	Condition	Cycle of management	Record	Checked Item	Margin	Method of Inspection	Cycle of management	Record	Action
			Dry	Dryer Dry Jig	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter	Dry Condition Printed condition breakage	refer to Guide Sheet	Visual Inspection	all	Lot card	Rework
			Baking	Baking Hole mesh net	Temperature Belt speed	refer to Guide Sheet	1/week	Parameter C/Sheet	Breakage Pollution	refer to Guide Sheet	Visual Inspection	all	Lot card	Exhaust Rework
			aspect inspection						aspect	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot card production diary	Exhaust repair
			MARKING	Marking Machine					marking	Reference SPL	Visual Inspection	all	Lot card production diary	Rework Exhaust
			Electrical Characteristic	NETWORK Inspection Jig	proofreading Condition	refer to Guide Sheet	1/2hour	C/sheet	Electrical Characteristic	refer to Guide Sheet	Network	all	Lot card production diary	Exhaust repair
			aspect inspection						aspect dimension	Reference SPL refer to Guide Sheet	Visual Inspection microscope	all	Lot card production diary	Exhaust repair
Carrier cover reel			Taping						Quantity Direction aspect	refer to Guide Sheet	Manual	all	Lot card production diary	Rework
			shipper inspection	NETWORK Inspection Jig	proofreading Condition	refer to Guide Sheet	1/person	C/sheet	Electrical Characteristic aspect packing	refer to Guide Sheet	Network microscope Visual Inspection	refer to Guide Sheet	Result Paper	return Exhaust
packing box label			packing	bar code printer					packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	-	Rework
			packing inspection						packing P/N Quantity	refer to Guide Sheet	Visual Inspection	all	-	return

10. RoHS Data

1) Ceramic Powder



MATERIAL SAFETY DATA SHEET

KOM Corporation
No. 41-2 Chome, Tsukisan cho, Minato-ku, Nagoya, Japan
Electronic Ceramic Materials Department
TEL: (052)653-8554 FAX: (052)652-0035
Date Issued: January 27, 2006

[PRODUCT NAME & CHEMICAL NAME] IIF-23K (SD)

[SPECIFIC OF MATERIAL]

Classification of unit product or Mixed product: unit product
Element & Content: MgTiO_3 (48.8%), CaTiO_3 (41.7%)
Chemical Formula: ---
Official Generic No.: ---
(Chemical substances control law & Industry safety and health law)
Cn No.: MgTiO3(12032-20-3), CaTiO3(12049-60-2)
UN classification & U.N. No.: none

[HAZARDS INFORMATION]

Fire/Explosion hazard: not conflict with fire act
Toxicological hazard: no specific defect
Environmental hazard: no specific defect

[FIRST AID MEASURES]

Eye: Flush thoroughly with water, and contact a physician.
Skin: Wash thoroughly with water, then with soap. If irritation occurs, contact a physician.
Inhalation: In case of inhalation of dust, wash nasal cavity with warm water and gargle the throat. If big volume of dust, contact a physician.
Ingestion: In case of ingestion, wash mouth with water. If big volume, induce vomiting after drinking water, and contact a physician.

[FIRE-FIGHTING MEASURES]

Extinguishing method: not flammable
Extinguishing media: not flammable

(1/3)

2) Ag paste



3) Marking ink



Test Report No. F60601/LF-CT&GP06-07273

Date: March 31, 2006

Page 1 of 3

 To: PARTRON
 33, Banwol-d
 Taejon-eup
 Daejeon-city
 305-802-00
 Korea

The following merchandise was submitted and identified by the client as:

Commodity: INK(5135E)

SGS File No.: GP06-07273

Received Date: March 24, 2006

Test Performing Date: March 27, 2006

Test Performed: SGS Testing Korea tested the sample(s) selected by applicant with following results

Test Results: For further details, please refer to following page(s)

 Brendan Lee
 Mandy Jeong
 Judy Oh
 Jerry Jung
 (Testing Person)



Jeff Jang / Technical Mgr



Jason Han / Lab Director

SGS Testing Korea Co. Ltd.



Test Report No. F60601/LF-CT&GP06-07273

Date: March 31, 2006

Page 2 of 3

Sample No.: GP06-07273.001

Sample Description: INK(5135E)

Style/Item No.: N/A

Heavy Metals

Test Items	Unit	Test Method	MDL	Results
Cadmium(Cd)	mg/kg	US EPA 3050B(1996), US EPA 6010B(1996)	0.5	N.D.
Lead (Pb)	mg/kg	US EPA 3050B(1996), US EPA 6010B(1996)	5	N.D.
Mercury (Hg)	mg/kg	US EPA 3052(1996), US EPA 6010B(1996)	2	N.D.
Hexavalent Chromium (Cr VI)	mg/kg	US EPA 3060A(1996), US EPA 7198A(1992)	1	N.D.

Flame Retardants-PBBs/PBDEs

Test Items	Unit	Test Method	MDL	Results
Monobromobiphenyl	ppm	US EPA 3540C, GC/MS	5	N.D.
Di bromobiphenyl	ppm	US EPA 3540C, GC/MS	5	N.D.
Tribromobiphenyl	ppm	US EPA 3540C, GC/MS	5	N.D.
Tetrabromobiphenyl	ppm	US EPA 3540C, GC/MS	5	N.D.
Pentabromobiphenyl	ppm	US EPA 3540C, GC/MS	5	N.D.
Octabromobiphenyl	ppm	US EPA 3540C, GC/MS	5	N.D.
Nonabromobiphenyl	ppm	US EPA 3540C, GC/MS	5	N.D.
Decabromobiphenyl	ppm	US EPA 3540C, GC/MS	5	N.D.
Monobromobiphenyl ether	ppm	US EPA 3540C, GC/MS	5	N.D.
Di bromobiphenyl ether	ppm	US EPA 3540C, GC/MS	5	N.D.
Tribromobiphenyl ether	ppm	US EPA 3540C, GC/MS	5	N.D.
Tetrabromobiphenyl ether	ppm	US EPA 3540C, GC/MS	5	N.D.
Pentabromobiphenyl ether	ppm	US EPA 3540C, GC/MS	5	N.D.
Hexabromobiphenyl ether	ppm	US EPA 3540C, GC/MS	5	N.D.
Octabromobiphenyl ether	ppm	US EPA 3540C, GC/MS	5	N.D.
Nonabromobiphenyl ether	ppm	US EPA 3540C, GC/MS	5	N.D.
Decabromobiphenyl ether	ppm	US EPA 3540C, GC/MS	5	N.D.

NOTE: (1) N.D. = Not detected. (<MDL)

(2) ppm = mg/kg

(3) MDL = Method Detection Limit

(4) = No regulation

(5) = Qualitative analysis (No Unit)

(6) = Negative = Undetectable / Positive = Detectable

This Test Report is issued by the Company subject to its General Conditions of Service printed elsewhere. Attention is drawn to the limitations of liability, indemnification and jurisdictional issues defined therein. The results shown in this test report refer only to the sample(s) tested unless otherwise stated. This Test Report cannot be reproduced, except in full, without prior written permission of the Company.

This Test Report is issued by the Company subject to its General Conditions of Service printed elsewhere. Attention is drawn to the limitations of liability, indemnification and jurisdictional issues defined therein. The results shown in this test report refer only to the sample(s) tested unless otherwise stated. This Test Report cannot be reproduced, except in full, without prior written permission of the Company.